FAIRCHILD SEMICONDUCTOR™

October 1991
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# SCAN18541T
# Non-Inverting Line Driver with 3-STATE Outputs

## General Description

The SCAN18541T is a high speed, low-power line driver featuring separate data inputs organized into dual 9-bit bytes with byte-oriented paired output enable control signals. This device is compliant with IEEE 1149.1 Standard Test Access Port and Boundary Scan Architecture with the incorporation of the defined boundary-scan test logic and test access port consisting of Test Data Input (TDI), Test Data Out (TDO), Test Mode Select (TMS), and Test Clock (TCK).

## Features

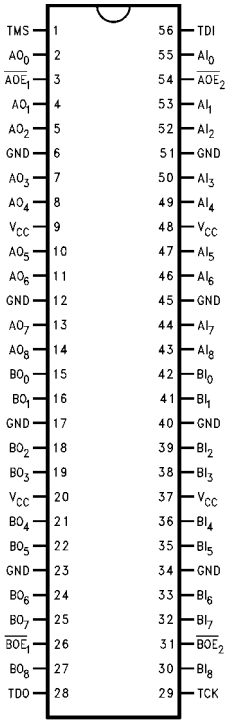
- IEEE 1149.1 (JTAG) Compliant
- Dual output enable signals per byte
- 3-STATE outputs for bus-oriented applications
- 9-bit data busses for parity applications
- Reduced-swing outputs source 32 mA/sink 64 mA
- Guaranteed to drive 50Ω transmission line to TTL input levels of 0.8V and 2.0V
- TTL compatible inputs
- 25 mil pitch SSOP (Shrink Small Outline Package)
- Includes CLAMP and HIGHZ instructions
- Member of Fairchild's SCAN Products

## Ordering Code:

| Order Number | Package Number | Package Description |
|---|---|---|
| SCAN18541TSSC | MS56A | 56-Lead Shrink Small Outline Package (SSOP), JEDEC MO-118, 0.300 Wide |

Devices also available in Tape and Reel. Specify by appending the suffix letter "X" to the ordering code.

## Connection Diagram




## Pin Names

| Pin Names | Description |
|---|---|
| $AI_{(0–8)}$ | Input Pins, A Side |
| $BI_{(0–8)}$ | Input Pins, B Side |
| $\overline{AOE}_1$, $\overline{AOE}_2$ | 3-STATE Output Enable Input Pins, A Side |
| $\overline{BOE}_1$, $\overline{BOE}_2$ | 3-STATE Output Enable Input Pins, B Side |
| $AO_{(0–8)}$ | Output Pins, A Side |
| $AO_{(0–8)}$ | Output Pins, B Side |

## Truth Tables

| Inputs | | | $AO_{(0–8)}$ |
|---|---|---|---|
| $\overline{AOE}_1$ | $\overline{AOE}_2$ | $AI_{(0–8)}$ | |
| L | L | H | H |
| H | X | X | Z |
| X | H | X | Z |
| L | L | L | L |

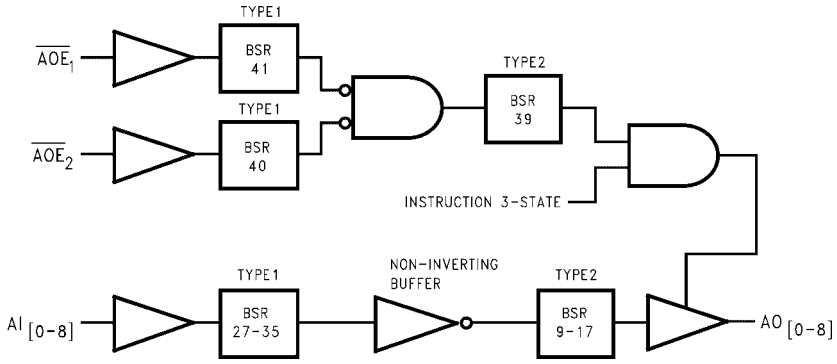
| Inputs | | | $BO_{(0–8)}$ |
|---|---|---|---|
| $\overline{BOE}_1$ | $\overline{BOE}_2$ | $BI_{(0–8)}$ | |
| L | L | H | H |
| H | X | X | Z |
| X | H | X | Z |
| L | L | L | L |

H = HIGH Voltage Level X = Immaterial
L = LOW Voltage Level Z = High Impedance

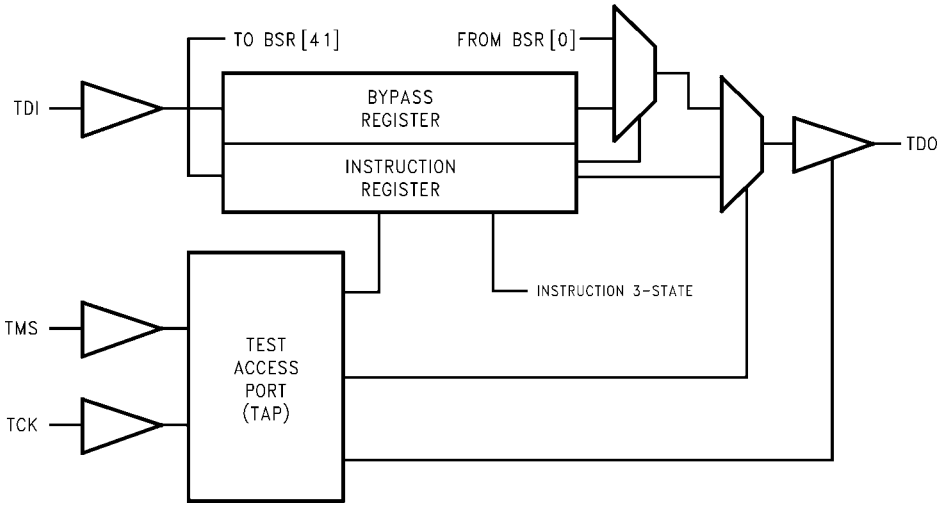
 

## Block Diagrams

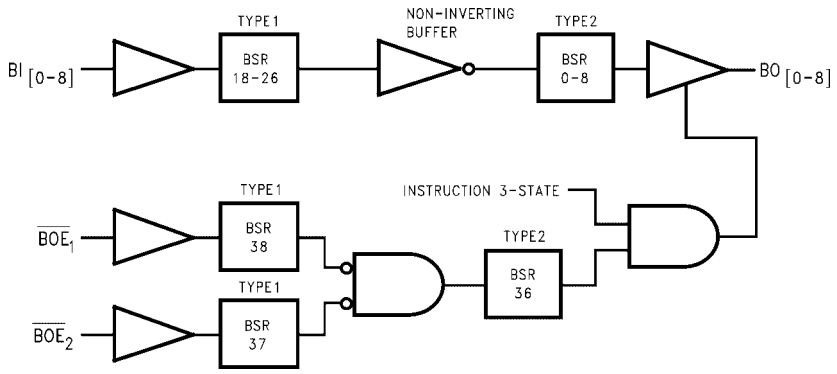
**Byte A**




**Tap Controller**




**Byte B**




**Note:** BSR stands for Boundary Scan Register.

## Description of Boundary-Scan Circuitry

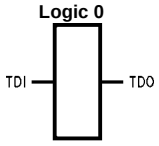
The scan cells used in the BOUNDARY-SCAN register are one of the following two types depending upon their location. Scan cell TYPE1 is intended to solely observe system data, while TYPE2 has the additional ability to control system data.

Scan cell TYPE1 is located on each system input pin while scan cell TYPE2 is located at each system output pin as well as at each of the two internal active-high output enable signals. AOE controls the activity of the A-outputs while BOE controls the activity of the B-outputs. Each will activate their respective outputs by loading a logic high.

The BYPASS register is a single bit shift register stage identical to scan cell TYPE1. It captures a fixed logic low.

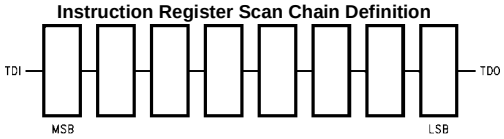
**Bypass Register Scan Chain Definition**

**Logic 0**




The INSTRUCTION register is an 8-bit register which captures the default value of 10000001. The two least significant bits of this captured value (01) are required by IEEE Std 1149.1. The upper six bits are unique to the SCAN18541T device. SCAN CMOS Test Access Logic devices do not include the IEEE 1149.1 optional identification register. Therefore, this unique captured value can be used as a "pseudo ID" code to confirm that the correct device is placed in the appropriate location in the boundary scan chain.

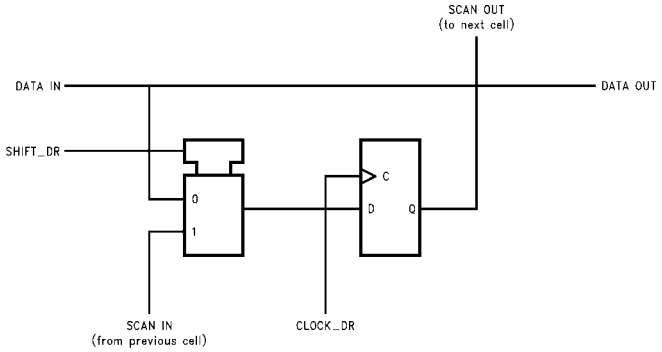
**Instruction Register Scan Chain Definition**



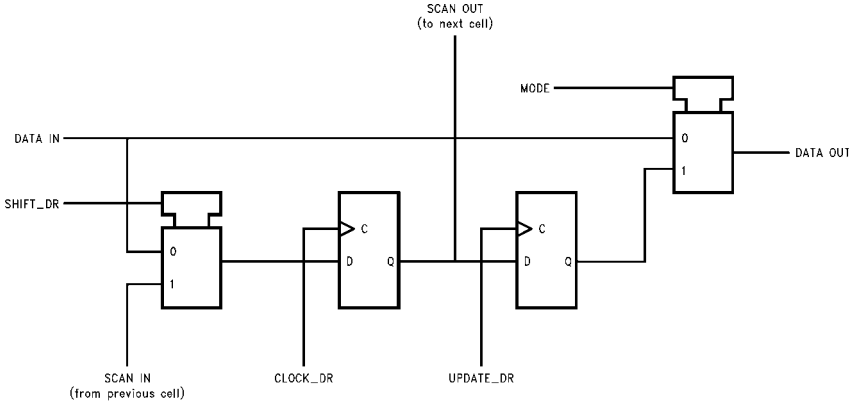

**MSB→LSB**

| Instruction Code | Instruction |
|---|---|
| 00000000 | EXTEST |
| 10000001 | SAMPLE/PRELOAD |
| 10000010 | CLAMP |
| 00000011 | HIGH-Z |
| All Others | BYPASS |

**Scan Cell TYPE1**

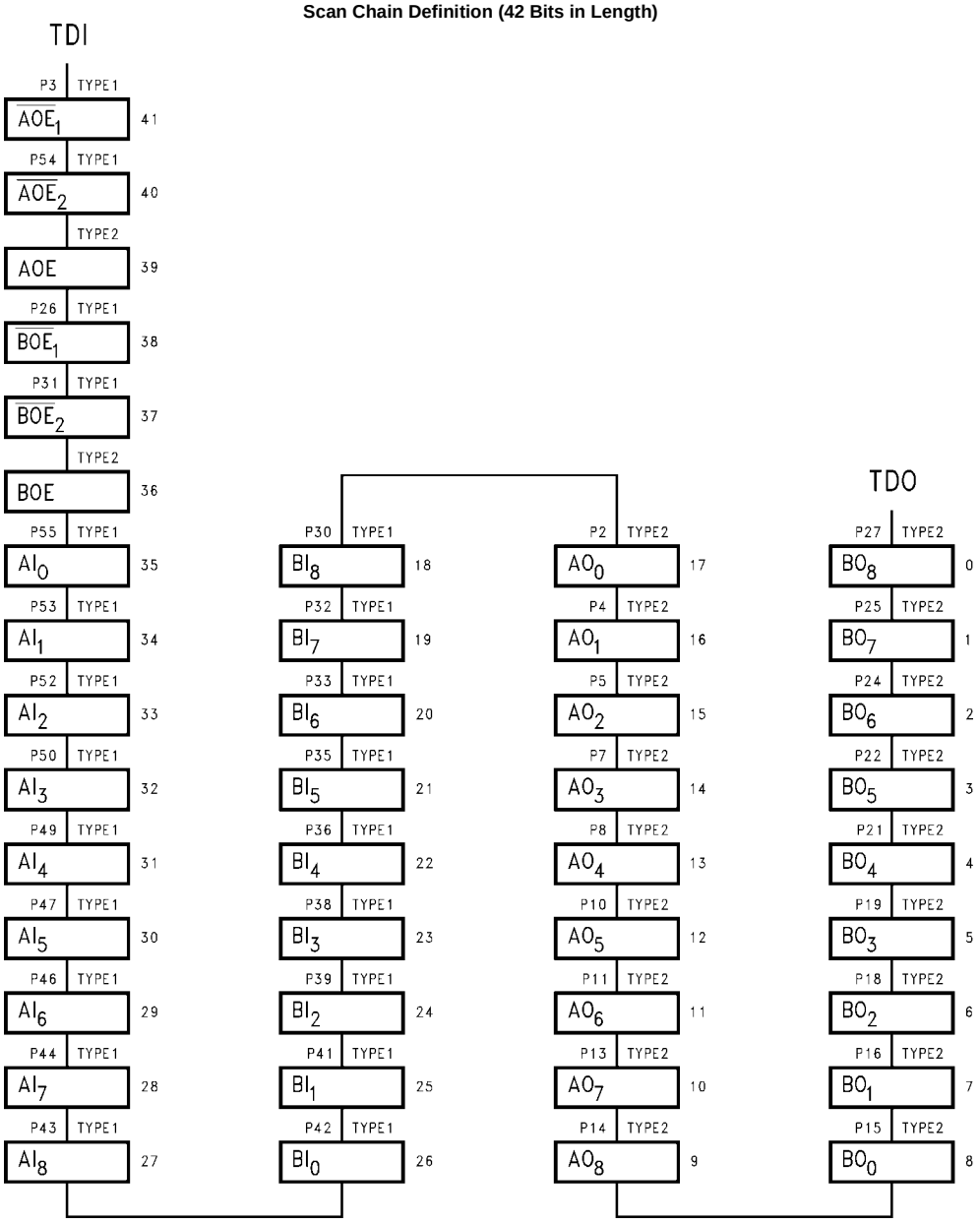



**Scan Cell TYPE2**



## Description of Boundary-Scan Circuitry (Continued)

**Boundary-Scan Register**
**Scan Chain Definition (42 Bits in Length)**



## Description of Boundary-Scan Circuitry (Continued)

**Boundary-Scan Register Definition Index**

| Bit No. | Pin Name | Pin No. | Pin Type | Scan Cell Type | |
|---|---|---|---|---|---|
| 41 | $\overline{AOE}_1$ | 3 | Input | TYPE1 | Control Signals |
| 40 | $\overline{AOE}_2$ | 54 | Input | TYPE1 | |
| 39 | AOE | | Internal | TYPE2 | |
| 38 | $\overline{BOE}_1$ | 26 | Input | TYPE1 | |
| 37 | $\overline{BOE}_2$ | 31 | Input | TYPE1 | |
| 36 | BOE | | Internal | TYPE2 | |
| 35 | $AI_0$ | 55 | Input | TYPE1 | A–in |
| 34 | $AI_1$ | 53 | Input | TYPE1 | |
| 33 | $AI_2$ | 52 | Input | TYPE1 | |
| 32 | $AI_3$ | 50 | Input | TYPE1 | |
| 31 | $AI_4$ | 49 | Input | TYPE1 | |
| 30 | $AI_5$ | 47 | Input | TYPE1 | |
| 29 | $AI_6$ | 46 | Input | TYPE1 | |
| 28 | $AI_7$ | 44 | Input | TYPE1 | |
| 27 | $AI_8$ | 43 | Input | TYPE1 | |
| 26 | $BI_0$ | 42 | Input | TYPE1 | B–in |
| 25 | $BI_1$ | 41 | Input | TYPE1 | |
| 24 | $BI_2$ | 39 | Input | TYPE1 | |
| 23 | $BI_3$ | 38 | Input | TYPE1 | |
| 22 | $BI_4$ | 36 | Input | TYPE1 | |
| 21 | $BI_5$ | 35 | Input | TYPE1 | |
| 20 | $BI_6$ | 33 | Input | TYPE1 | |
| 19 | $BI_7$ | 32 | Input | TYPE1 | |
| 18 | $BI_8$ | 30 | Input | TYPE1 | |
| 17 | $AO_0$ | 2 | Output | TYPE2 | A–out |
| 16 | $AO_1$ | 4 | Output | TYPE2 | |
| 15 | $AO_2$ | 5 | Output | TYPE2 | |
| 14 | $AO_3$ | 7 | Output | TYPE2 | |
| 13 | $AO_4$ | 8 | Output | TYPE2 | |
| 12 | $AO_5$ | 10 | Output | TYPE2 | |
| 11 | $AO_6$ | 11 | Output | TYPE2 | |
| 10 | $AO_7$ | 13 | Output | TYPE2 | |
| 9 | $AO_8$ | 14 | Output | TYPE2 | |
| 8 | $BO_0$ | 15 | Output | TYPE2 | B–out |
| 7 | $BO_1$ | 16 | Output | TYPE2 | |
| 6 | $BO_2$ | 18 | Output | TYPE2 | |
| 5 | $BO_3$ | 19 | Output | TYPE2 | |
| 4 | $BO_4$ | 21 | Output | TYPE2 | |
| 3 | $BO_5$ | 22 | Output | TYPE2 | |
| 2 | $BO_6$ | 24 | Output | TYPE2 | |
| 1 | $BO_7$ | 25 | Output | TYPE2 | |
| 0 | $BO_8$ | 27 | Output | TYPE2 | |

## Absolute Maximum Ratings(Note 1)

| | |
|---|---|
| Supply Voltage ($V_{CC}$) | −0.5V to +7.0V |
| DC Input Diode Current ($I_{IK}$) | |
| $V_I$ = −0.5V | −20 mA |
| $V_I$ = $V_{CC}$ +0.5V | +20 mA |
| DC Output Diode Current ($I_{OK}$) | |
| $V_O$ = −0.5V | −20 mA |
| $V_O$ = $V_{CC}$ +0.5V | +20 mA |
| DC Output Voltage ($V_O$) | −0.5V to $V_{CC}$ +0.5V |
| DC Output Source/Sink Current ($I_O$) | ±70 mA |
| DC $V_{CC}$ or Ground Current | |
| Per Output Pin | ±70 mA |
| Junction Temperature | |
| SSOP | +140°C |
| Storage Temperature | −65°C to +150°C |
| ESD (Min) | 2000V |

## Recommended Operating Conditions

| | |
|---|---|
| Supply Voltage ($V_{CC}$) | |
| SCAN Products | 4.5V to 5.5V |
| Input Voltage ($V_I$) | 0V to $V_{CC}$ |
| Output Voltage ($V_O$) | 0V to $V_{CC}$ |
| Operating Temperature ($T_A$) | −40°C to +85°C |
| Minimum Input Edge Rate ΔV/Δt | 125 mV/ns |
| $V_{IN}$ from 0.8V to 2.0V | |
| $V_{CC}$ @ 4.5V, 5.5V | |

**Note 1:** Absolute maximum ratings are those values beyond which damage to the device may occur. The databook specifications should be met, without exception, to ensure that the system design is reliable over its power supply, temperature, and output/input loading variables. Fairchild does not recommend operation of SCAN circuits outside databook specifications.

## DC Electrical Characteristics

| Symbol | Parameter | $V_{CC}$ (V) | $T_A$ = +25°C Typ | $T_A$ = −40°C to +85°C Guaranteed Limits | | Units | Conditions |
|---|---|---|---|---|---|---|---|
| $V_{IH}$ | Minimum HIGH Input Voltage | 4.5 | 1.5 | 2.0 | 2.0 | V | $V_{OUT}$ = 0.1V or $V_{CC}$ −0.1V |
| | | 5.5 | 1.5 | 2.0 | 2.0 | | |
| $V_{IL}$ | Maximum LOW Input Voltage | 4.5 | 1.5 | 0.8 | 0.8 | V | $V_{OUT}$ = 0.1V or $V_{CC}$ −0.1V |
| | | 5.5 | 1.5 | 0.8 | 0.8 | | |
| $V_{OH}$ | Minimum HIGH Output Voltage | 4.5 | | 3.15 | 3.15 | V | $I_{OUT}$ = −50 μA |
| | | 5.5 | | 4.15 | 4.15 | | |
| | (Note 3) | 4.5 | | 2.4 | 2.4 | V | $V_{IN}$ = $V_{IL}$ or $V_{IH}$ $I_{OH}$ = −32 mA |
| | | 5.5 | | 2.4 | 2.4 | | |
| | | 4.5 | | 2.4 | | V | $V_{IN}$ = $V_{IL}$ or $V_{IH}$ $I_{OH}$ = −24 mA |
| | | 5.5 | | 2.4 | | | |
| $V_{OL}$ | Maximum LOW Output Voltage | 4.5 | | 0.1 | 0.1 | V | $I_{OUT}$ = 50 μA |
| | | 5.5 | | 0.1 | 0.1 | | |
| | (Note 3) | 4.5 | | 0.55 | 0.55 | V | $V_{IN}$ = $V_{IL}$ or $V_{IH}$ $I_{OL}$ = 64 mA |
| | | 5.5 | | 0.55 | 0.55 | | |
| | | 4.5 | | 0.55 | | V | $V_{IN}$ = $V_{IL}$ or $V_{IH}$ $I_{OL}$ = 48 mA |
| | | 5.5 | | 0.55 | | | |
| $I_{IN}$ | Maximum Input Leakage Current | 5.5 | | ±0.1 | ±1.0 | μA | $V_I$ = $V_{CC}$, GND |
| $I_{IN}$ TDI, TMS | Maximum Input Leakage | 5.5 | | 2.8 | 3.6 | μA | $V_I$ = $V_{CC}$ |
| | | | | −385 | −385 | μA | $V_I$ = GND |
| | Minimum Input Leakage | 5.5 | | −160 | −160 | μA | $V_I$ = GND |
| $I_{OLD}$ | Minimum Dynamic | 5.5 | | 94 | 94 | mA | $V_{OLD}$ = 0.8V Max |
| $I_{OHD}$ | Output Current (Note 2) | | | −40 | −40 | mA | $V_{OHD}$ = 2.0V Min |
| $I_{OZ}$ | Maximum Output Leakage Current | 5.5 | | ±0.5 | ±5.0 | μA | $V_I$ (OE) = $V_{IL}$, $V_{IH}$ |
| $I_{OS}$ | Output Short Circuit Current | 5.5 | | −100 | −100 | mA (min) | $V_O$ = 0V |
| $I_{CC}$ | Maximum Quiescent Supply Current | 5.5 | | 16.0 | 88 | μA | $V_O$ = Open TDI, TMS = $V_{CC}$ |
| | | 5.5 | | 750 | 820 | μA | $V_O$ = Open TDI, TMS = GND |

## DC Electrical Characteristics (Continued)

| Symbol | Parameter | $V_{CC}$ (V) | $T_A = +25°C$ | $T_A = -40°C$ to $+85°C$ | | Units | Conditions |
|---|---|---|---|---|---|---|---|
| | | | Typ | Guaranteed Limits | | | |
| $I_{CCt}$ | Maximum $I_{CC}$ Per Input | 5.5 | | 2.0 | 2.0 | mA | $V_I = V_{CC}-2.1V$ |
| | | 5.5 | | 2.15 | 2.15 | mA | $V_I = V_{CC}-2.1V$ TDI/TMS Pin, Test One with the Other Floating |

**Note 2:** Maximum test duration 2.0 ms, one output loaded at a time.

**Note 3:** All outputs loaded; thresholds associated with output under test.

## Noise Specifications

| Symbol | Parameter | $V_{CC}$ (V) | $T_A = +25°C$ | | $T_A = -40°C$ to $+85°C$ | Units |
|---|---|---|---|---|---|---|
| | | | Typ | Guaranteed Limits | | |
| $V_{OLP}$ | Maximum HIGH Output Noise (Note 4)(Note 5) | 5.0 | 1.0 | 1.5 | | V |
| $V_{OLV}$ | Minimum LOW Output Noise (Note 4)(Note 5) | 5.0 | –0.6 | –1.2 | | V |
| $V_{OHP}$ | Maximum Overshoot (Note 4)(Note 6) | 5.0 | $V_{OH}+1.0$ | $V_{OH}+1.5$ | | V |
| $V_{OHV}$ | Minimum $V_{CC}$ Droop (Note 4)(Note 6) | 5.0 | $V_{OH}-1.0$ | $V_{OH}-1.8$ | | V |
| $V_{IHD}$ | Minimum HIGH Dynamic Input Voltage Level (Note 6)(Note 7) | 5.5 | 1.6 | 2.0 | 2.0 | V |
| $V_{ILD}$ | Maximum LOW Dynamic Input Voltage Level (Note 6)(Note 7) | 5.5 | 1.4 | 0.8 | 0.8 | V |

**Note 4:** Maximum number of outputs that can switch simultaneously is n. (n-1) outputs are switched LOW and one output held LOW.

**Note 5:** Maximum number of outputs that can switch simultaneously is n. (n-1) outputs are switched HIGH and one output held HIGH.

**Note 6:** Worst case package.

**Note 7:** Maximum number of data inputs (n) switching. (n-1) input switching 0V to 3V. Input under test switching 3V to threshold ($V_{ILD}$).

## AC Electrical Characteristics

Normal Operation:

| Symbol | Parameter | $V_{CC}$ (V) (Note 8) | $T_A = +25°C$, $C_L = 50$ pF | | | $T_A = -40°C$ to $+85°C$, $C_L = 50$ pF | | Units |
|---|---|---|---|---|---|---|---|---|
| | | | Min | Typ | Max | Min | Max | |
| $t_{PLH}$, $t_{PHL}$ | Propagation Delay Data to Q | 5.0 | 2.5 | | 9.0 | 2.5 | 9.8 | ns |
| | | | 2.5 | | 9.0 | 2.5 | 9.8 | |
| $t_{PLZ}$, $t_{PHZ}$ | Disable Time | 5.0 | 1.5 | | 10.2 | 1.5 | 10.7 | ns |
| | | | 1.5 | | 10.2 | 1.5 | 10.7 | |
| $t_{PZL}$, $t_{PZH}$ | Enable Time | 5.0 | 2.0 | | 11.8 | 2.0 | 12.8 | ns |
| | | | 2.0 | | 9.5 | 2.0 | 10.5 | |

**Note 8:** Voltage Range 5.0 is 5.0V ± 0.5V.

## AC Electrical Characteristics

Scan Test Operation:

| Symbol | Parameter | $V_{CC}$ (V) (Note 9) | $T_A = +25°C$, $C_L = 50$ pF | | | $T_A = -40°C$ to $+85°C$, $C_L = 50$ pF | | Units |
|---|---|---|---|---|---|---|---|---|
| | | | Min | Typ | Max | Min | Max | |
| $t_{PLH}$, $t_{PHL}$ | Propagation Delay TCK to TDO | 5.0 | 3.5 | | 13.2 | 3.5 | 14.5 | ns |
| | | | 3.5 | | 13.2 | 3.5 | 14.5 | |
| $t_{PLZ}$, $t_{PHZ}$ | Disable Time TCK to TDO | 5.0 | 2.5 | | 11.5 | 2.5 | 11.9 | ns |
| | | | 2.5 | | 11.5 | 2.5 | 11.9 | |
| $t_{PZL}$, $t_{PZH}$ | Enable Time TCK to TDO | 5.0 | 3.0 | | 14.5 | 3.0 | 15.8 | ns |
| | | | 3.0 | | 14.5 | 3.0 | 15.8 | |
| $t_{PLH}$, $t_{PHL}$ | Propagation Delay TCK to Data Out During Update-DR State | 5.0 | 5.0 | | 18.0 | 5.0 | 19.8 | ns |
| | | | 5.0 | | 18.0 | 5.0 | 19.8 | |
| $t_{PLH}$, $t_{PHL}$ | Propagation Delay TCK to Data Out During Update-IR State | 5.0 | 5.0 | | 18.6 | 5.0 | 20.2 | ns |
| | | | 5.0 | | 18.6 | 5.0 | 20.2 | |
| $t_{PLH}$, $t_{PHL}$ | Propagation Delay TCK to Data Out During Test Logic Reset State | 5.0 | 5.5 | | 19.9 | 5.5 | 21.5 | ns |
| | | | 5.5 | | 19.9 | 5.5 | 21.5 | |
| $t_{PLZ}$, $t_{PHZ}$ | Propagation Delay TCK to Data Out During Update-DR State | 5.0 | 4.0 | | 16.4 | 4.0 | 18.2 | ns |
| | | | 4.0 | | 16.4 | 4.0 | 18.2 | |
| $t_{PLZ}$, $t_{PHZ}$ | Propagation Delay TCK to Data Out During Update-IR State | 5.0 | 5.0 | | 19.5 | 5.0 | 20.8 | ns |
| | | | 5.0 | | 19.5 | 5.0 | 20.8 | |
| $t_{PLZ}$, $t_{PHZ}$ | Propagation Delay TCK to Data Out During Test Logic Reset State | 5.0 | 5.0 | | 19.9 | 5.0 | 21.5 | ns |
| | | | 5.0 | | 19.9 | 5.0 | 21.5 | |
| $t_{PZL}$, $t_{PZH}$ | Propagation Delay TCK to Data Out During Update-DR State | 5.0 | 5.0 | | 18.9 | 5.0 | 20.9 | ns |
| | | | 5.0 | | 18.9 | 5.0 | 20.9 | |
| $t_{PZL}$, $t_{PZH}$ | Propagation Delay TCK to Data Out During Update-IR State | 5.0 | 6.5 | | 22.4 | 6.5 | 24.2 | ns |
| | | | 6.5 | | 22.4 | 6.5 | 24.2 | |
| $t_{PZL}$, $t_{PZH}$ | Propagation Delay TCK to Data Out During Test Logic Reset State | 5.0 | 7.0 | | 23.8 | 7.0 | 25.7 | ns |
| | | | 7.0 | | 23.8 | 7.0 | 25.7 | |

**Note:** All Propagation Delays involving TCK are measured from the falling edge of TCK.

**Note 9:** Voltage Range 5.0 is 5.0V ± 0.5V.

## AC Operating Requirements

Scan Test Operation:

| Symbol | Parameter | $V_{CC}$ (V) (Note 10) | $T_A = +25°C$ $C_L = 50$ pF | $T_A = -40°C$ to $+85°C$ $C_L = 50$ pF | Units |
|---|---|---|---|---|---|
| | | | Guaranteed Minimum | | |
| $t_S$ | Setup Time, H or L<br>Data to TCK (Note 11) | 5.0 | 3.0 | 3.0 | ns |
| $t_H$ | Hold Time, H or L<br>TCK to Data (Note 11) | 5.0 | 4.5 | 4.5 | ns |
| $t_S$ | Setup Time, H or L<br>$\overline{AOE}_n$, $\overline{BOE}_n$ to TCK (Note 12) | 5.0 | 3.0 | 3.0 | ns |
| $t_H$ | Hold Time, H or L<br>TCK to $\overline{AOE}_n$, $\overline{BOE}_n$ (Note 12) | 5.0 | 4.5 | 4.5 | ns |
| $t_S$ | Setup Time, H or L<br>Internal AOE, BOE, to TCK (Note 13) | 5.0 | 3.0 | 3.0 | ns |
| $t_H$ | Hold Time, H or L<br>TCK to Internal AOE, BOE (Note 13) | 5.0 | 3.0 | 3.0 | ns |
| $t_S$ | Setup Time, H or L<br>TMS to TCK | 5.0 | 8.0 | 8.0 | ns |
| $t_H$ | Hold Time, H or L<br>TCK to TMS | 5.0 | 2.0 | 2.0 | ns |
| $t_S$ | Setup Time, H or L<br>TDI to TCK | 5.0 | 4.0 | 4.0 | ns |
| $t_H$ | Hold Time, H or L<br>TCK to TDI | 5.0 | 4.5 | 4.5 | ns |
| $t_W$ | Pulse Width TCK | 5.0 | | | |
| | H | | 15.0 | 15.0 | ns |
| | L | | 5.0 | 5.0 | |
| $f_{MAX}$ | Maximum TCK<br>Clock Frequency | 5.0 | 25 | 25 | MHz |
| $T_{PU}$ | Wait Time, Power Up<br>to TCK | 5.0 | 100 | 100 | ns |
| $T_{DN}$ | Power Down Delay | 0.0 | 100 | 100 | ms |

**Note:** All Input Timing Delays involving TCK are measured from the rising edge of TCK.

**Note 10:** Voltage Range 5.0 is 5.0V ± 0.5V.

**Note 11:** This delay represents the timing relationship between the data input and TCK at the associated scan cells numbered 0-8, 9-17, 18-26 and 27-35.

**Note 12:** Timing pertains to BSR 37, 38, 40 and 41 only.

**Note 13:** This delay represents the timing relationship between AOE/BOE and TCK for scan cells 36 and 39 only.

## Extended AC Electrical Characteristics

| Symbol | Parameter | $T_A = +25°C$, $V_{CC} = 5.0V$, $C_L = 50$ pF, 18 Outputs Switching (Note 14) | | | $T_A = -40°C$ to $+85°C$, $V_{CC} = 5.0V \pm 0.5V$, $C_L = 250$ pF (Note 5) | | Units |
|---|---|---|---|---|---|---|---|
| | | Min | Typ | Max | Min | Max | |
| $t_{PLH}$, $t_{PHL}$ | Propagation Delay Data to Output | 3.0<br>3.0 | | 11.0<br>11.0 | 4.0<br>4.0 | 13.0<br>15.0 | ns |
| $t_{PZH}$, $t_{PZL}$ | Output Enable Time | 2.5<br>2.5 | | 11.5<br>14.0 | (Note 16) | | ns |
| $t_{PHZ}$, $t_{PLZ}$ | Output Disable Time | 2.0<br>2.0 | | 11.5<br>11.5 | (Note 17) | | ns |
| $t_{OSHL}$ (Note 18) | Pin to Pin Skew HL Data to Output | | 0.5 | 1.0 | | 1.0 | ns |
| $t_{OSLH}$ (Note 18) | Pin to Pin Skew LH Data to Output | | 0.5 | 1.0 | | 1.0 | ns |

**Note 14:** This specification is guaranteed but not tested. The limits apply to propagation delays for all paths described switching in phase (i.e., all LOW-to-HIGH, HIGH-to-LOW, etc.).

**Note 15:** This specification is guaranteed but not tested. The limits represent propagation delays with 250 pF load capacitors in place of the 50 pF load capacitors in the standard AC load. This specification pertains to single output switching only.

**Note 16:** 3-STATE delays are load dominated and have been excluded from the datasheet.

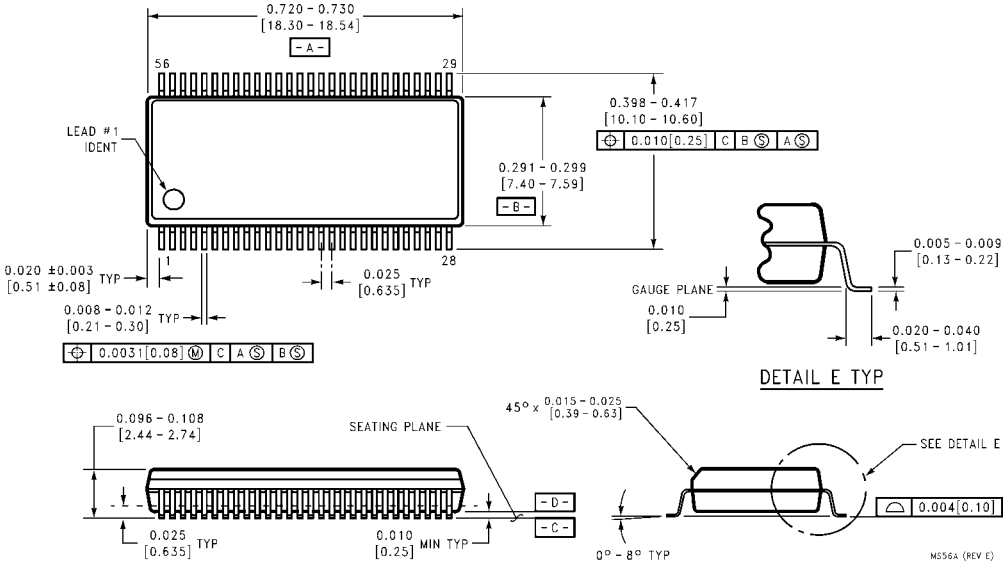
**Note 17:** The Output Disable Time is dominated by the RC network (500Ω, 250 pF) on the output and has been excluded from the datasheet.

**Note 18:** Skew is defined as the absolute value of the difference between the actual propagation delays for any two separate outputs of the same device. The specification applies to any outputs switching HIGH-to-LOW ($t_{OSHL}$), LOW-to-HIGH ($t_{OSLH}$), or any combination switching LOW-to-HIGH and/or HIGH-to-LOW.

## Capacitance

| Symbol | Parameter | Typ | Units | Conditions |
|---|---|---|---|---|
| $C_{IN}$ | Input Pin Capacitance | 4.0 | pF | $V_{CC} = 5.0V$ |
| $C_{OUT}$ | Output Pin Capacitance | 13.0 | pF | $V_{CC} = 5.0V$ |
| $C_{PD}$ | Power Dissipation Capacitance | 34.0 | pF | $V_{CC} = 5.0V$ |

## Physical Dimensions inches (millimeters) unless otherwise noted




**56-Lead Shrink Small Outline Package (SSOP), JEDEC MO-118, 0.300 Wide**
**Package Number MS56A**



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